

FIG. 1A
PRIOR ART

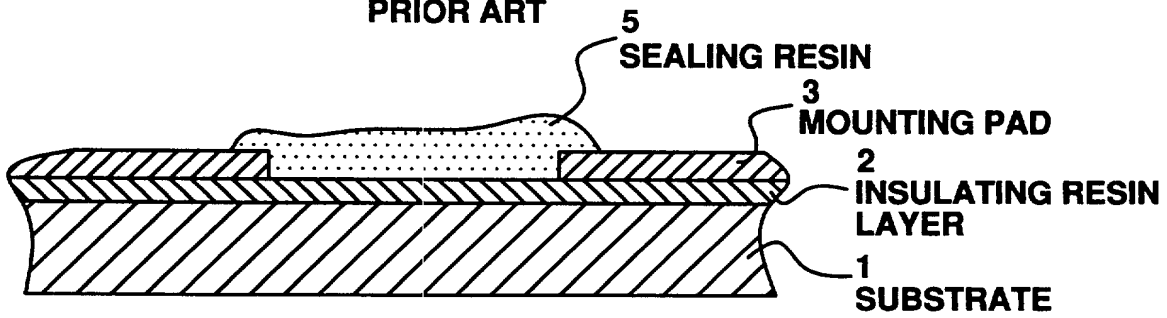
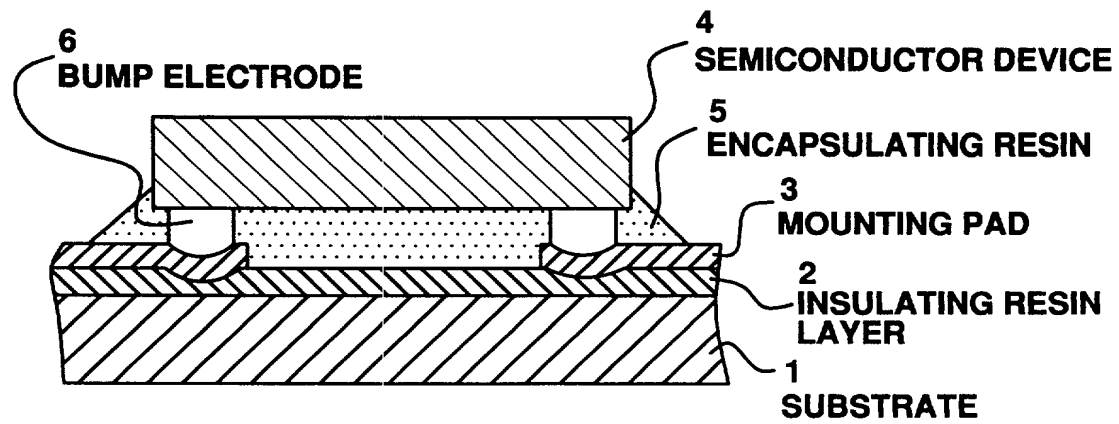
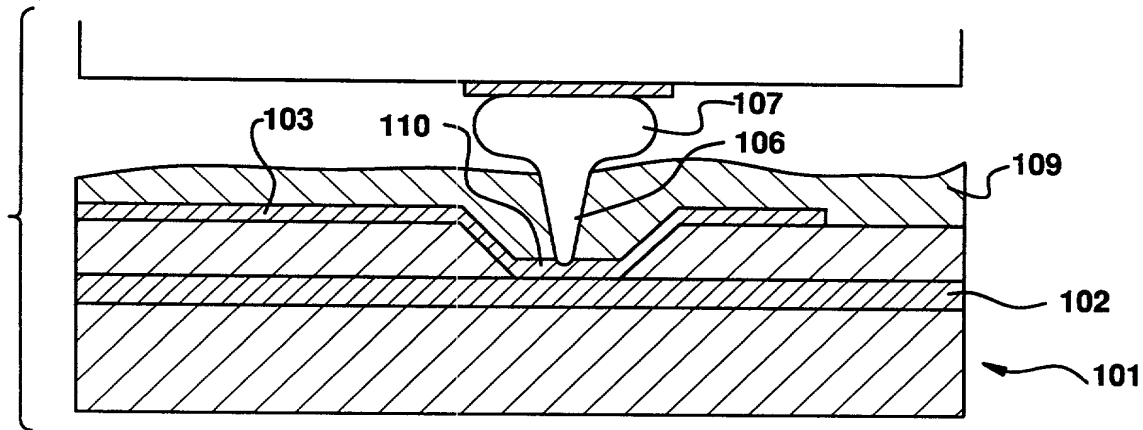


FIG. 1B
PRIOR ART



Variable	Mean	SD	Min	Max	Median	Q1	Q3	Mode	Skewness	Kurtosis	Jarque-Bera	Prob > Chi-Sq
Age	35.5	10.5	20	65	35	30	40	35	-0.1	3.2	0.001	0.999
Gender	0.5	0.5	0	1	0.5	0	1	0.5	0.0	0.0	0.000	0.000
Marital Status	0.7	0.5	0	1	0.7	0	1	0.7	0.0	0.0	0.000	0.000
Education	12.5	2.5	8	16	12	10	14	12	-0.2	1.5	0.001	0.999
Income	1500	500	500	3000	1200	800	1800	1200	-0.3	2.0	0.001	0.999
Health	0.8	0.4	0	1	0.8	0	1	0.8	0.0	0.0	0.000	0.000
Stress	0.6	0.5	0	1	0.6	0	1	0.6	0.0	0.0	0.000	0.000
Depression	0.4	0.5	0	1	0.4	0	1	0.4	0.0	0.0	0.000	0.000
Life Satisfaction	0.7	0.4	0	1	0.7	0	1	0.7	0.0	0.0	0.000	0.000
Resilience	0.6	0.5	0	1	0.6	0	1	0.6	0.0	0.0	0.000	0.000
Optimism	0.7	0.4	0	1	0.7	0	1	0.7	0.0	0.0	0.000	0.000
Self-Efficacy	0.8	0.4	0	1	0.8	0	1	0.8	0.0	0.0	0.000	0.000
Perceived Stress	0.5	0.5	0	1	0.5	0	1	0.5	0.0	0.0	0.000	0.000
Coping Strategies	0.6	0.5	0	1	0.6	0	1	0.6	0.0	0.0	0.000	0.000
Emotional Stability	0.7	0.4	0	1	0.7	0	1	0.7	0.0	0.0	0.000	0.000
Life Satisfaction	0.7	0.4	0	1	0.7	0	1	0.7	0.0	0.0	0.000	0.000
Resilience	0.6	0.5	0	1	0.6	0	1	0.6	0.0	0.0	0.000	0.000
Optimism	0.7	0.4	0	1	0.7	0	1	0.7	0.0	0.0	0.000	0.000
Self-Efficacy	0.8	0.4	0	1	0.8	0	1	0.8	0.0	0.0	0.000	0.000
Perceived Stress	0.5	0.5	0	1	0.5	0	1	0.5	0.0	0.0	0.000	0.000
Coping Strategies	0.6	0.5	0	1	0.6	0	1	0.6	0.0	0.0	0.000	0.000
Emotional Stability	0.7	0.4	0	1	0.7	0	1	0.7	0.0	0.0	0.000	0.000



A cross-sectional view of a semiconductor device. A central opening 107 is formed in a top layer 105. A layer 103 is located beneath the top layer 105. A layer 109 is located beneath layer 103. A layer 102 is located beneath layer 109. A layer 101 is located beneath layer 102. The opening 107 is filled with a material, and the layers 103, 109, and 102 are exposed around the opening.

FIG. 3A

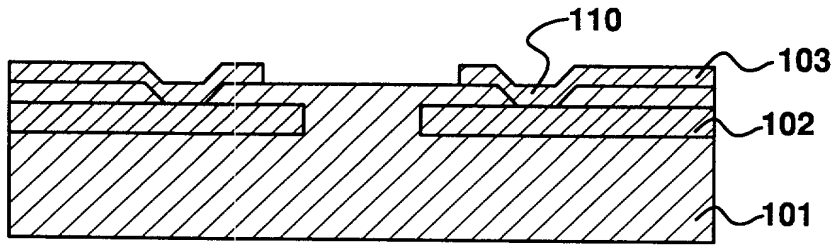


FIG. 3B

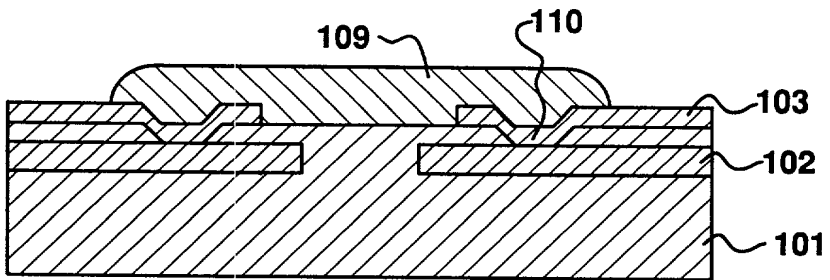


FIG. 3C

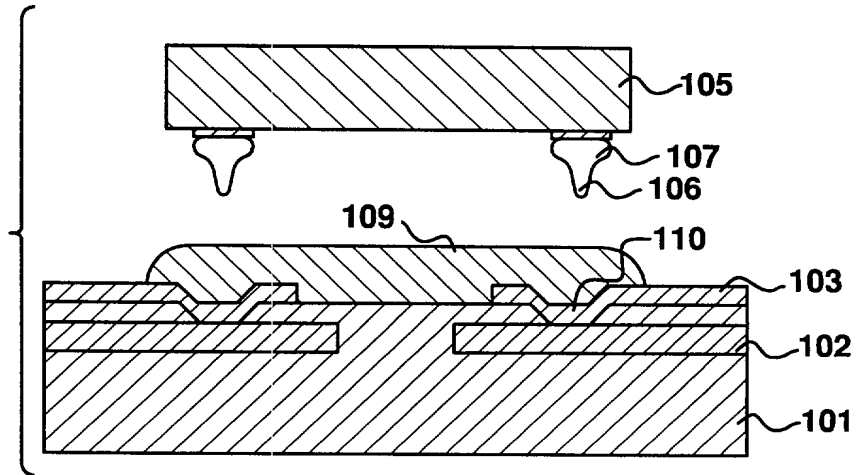


FIG. 3D

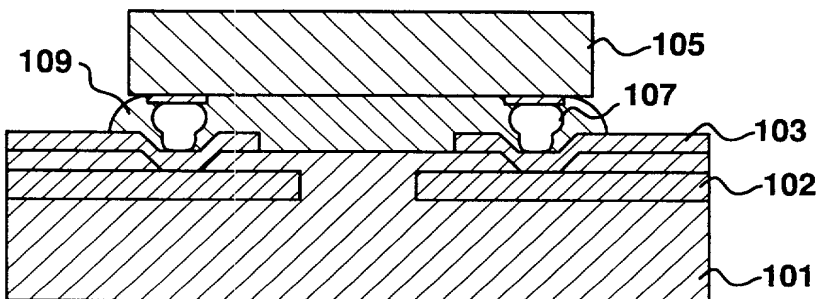


FIG. 4A

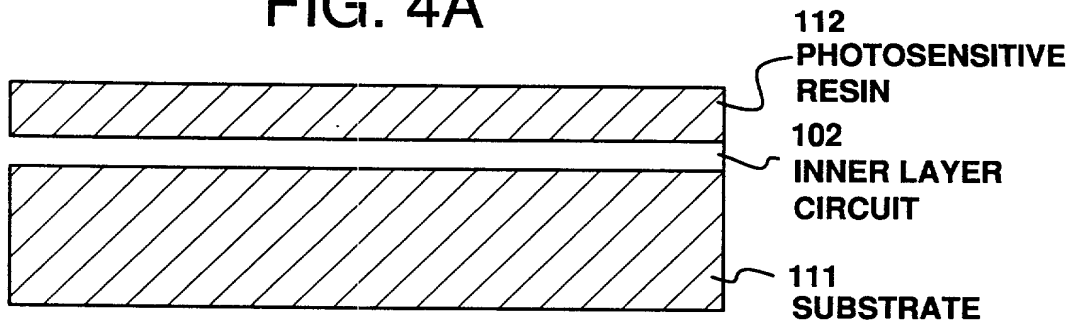


FIG. 4B

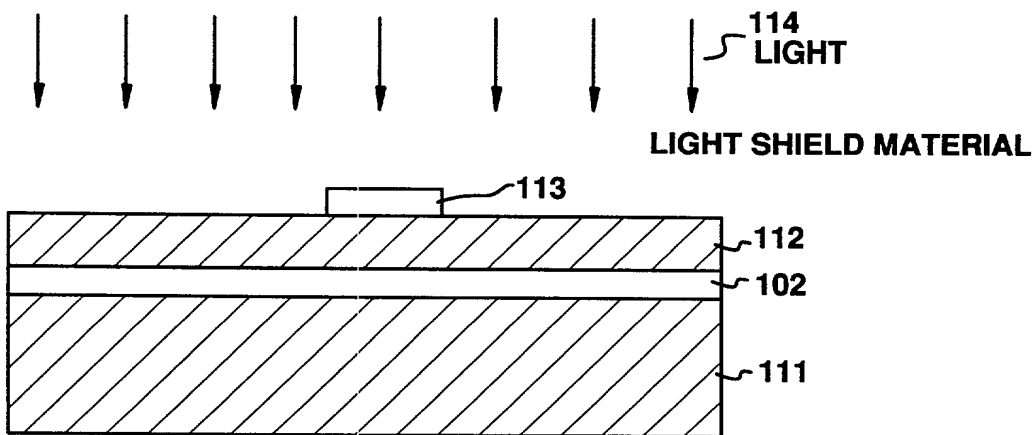


FIG. 4C

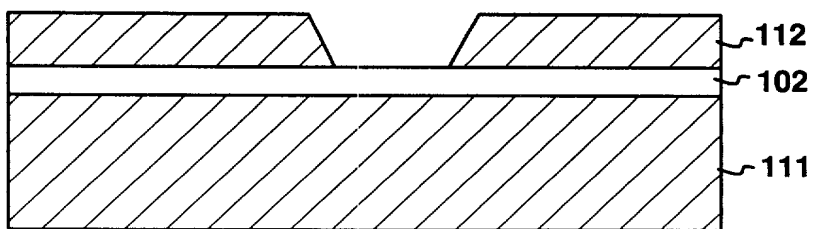


FIG. 4D

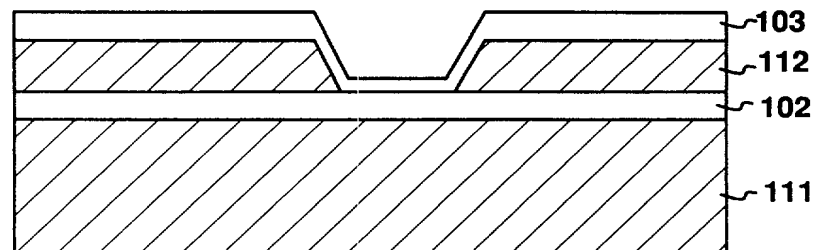


FIG. 5A

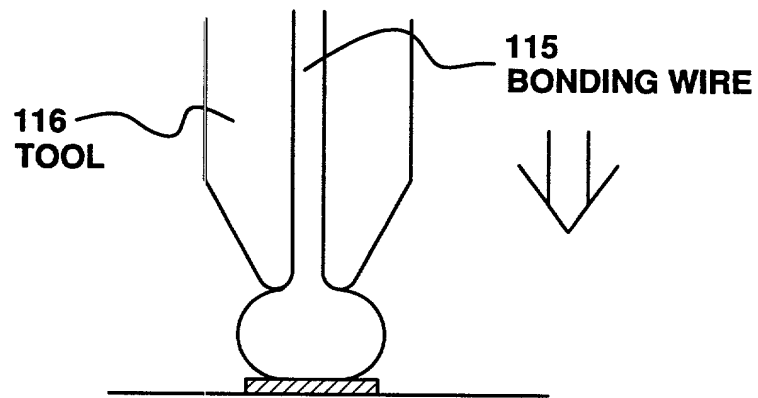


FIG. 5B

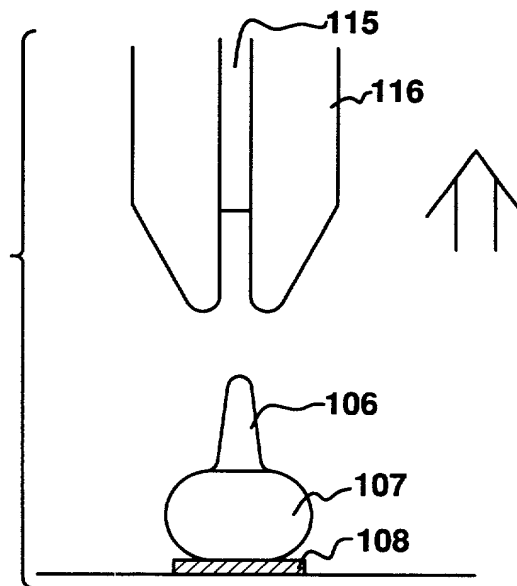
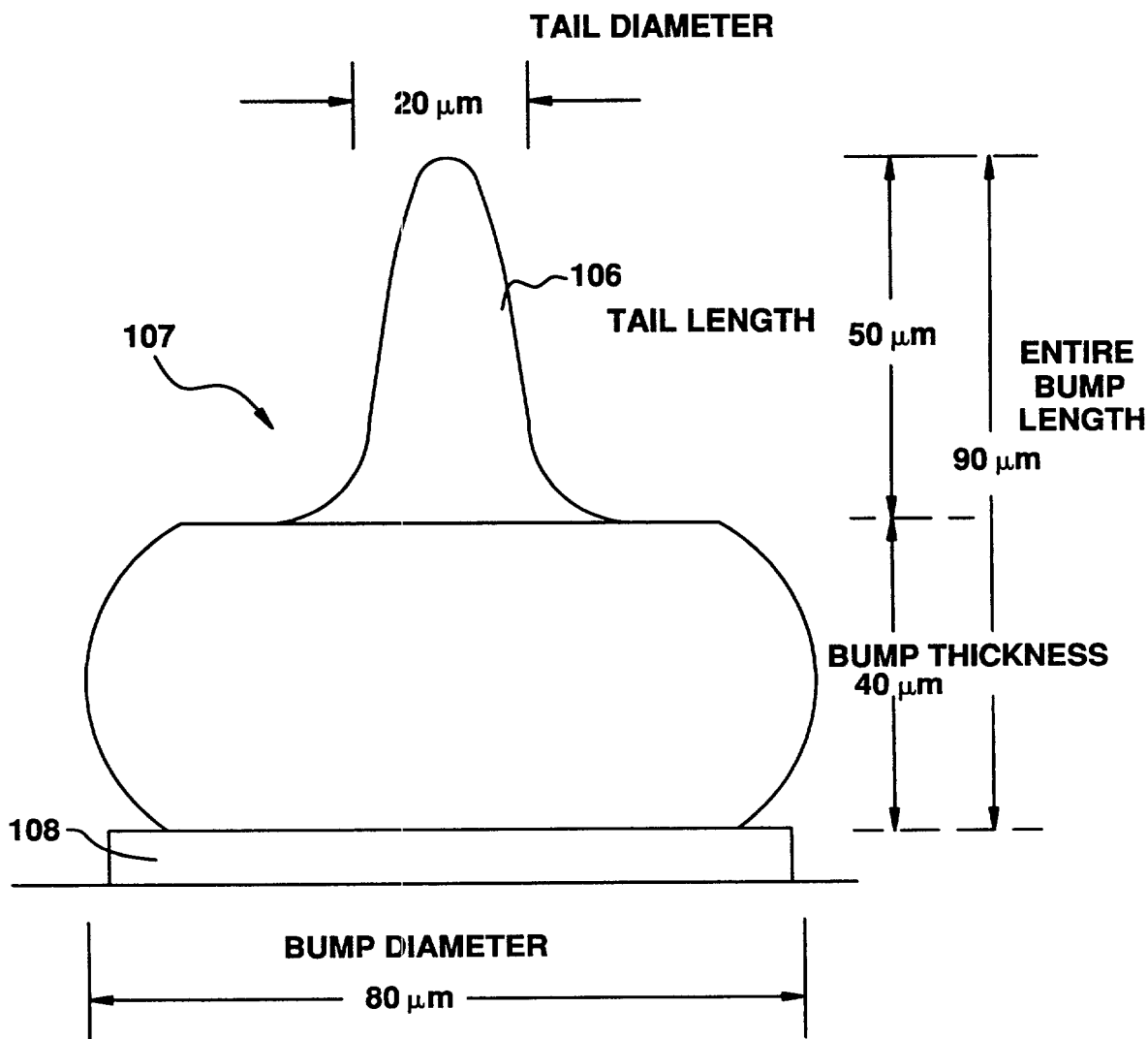


FIG. 6



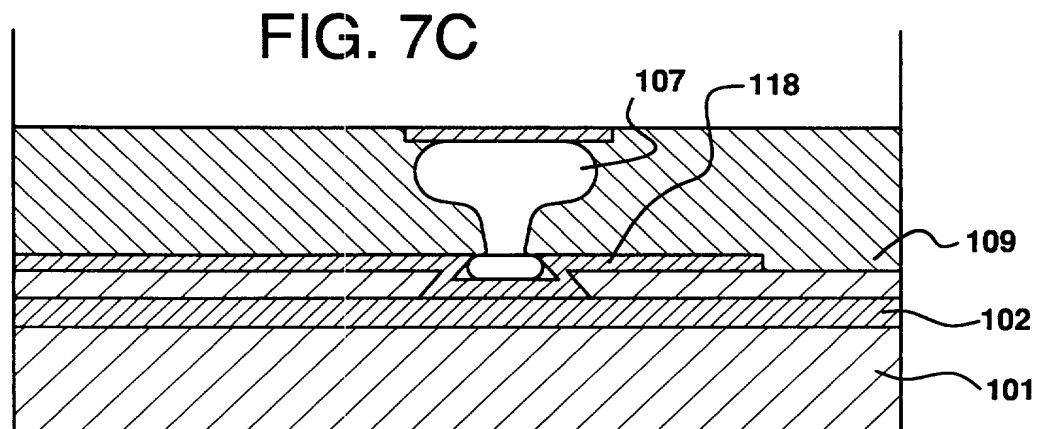
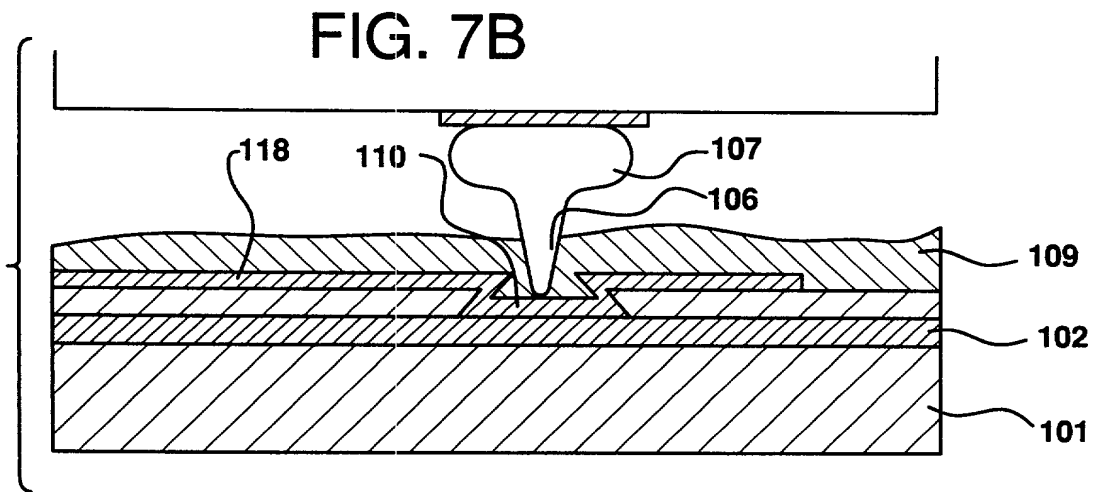
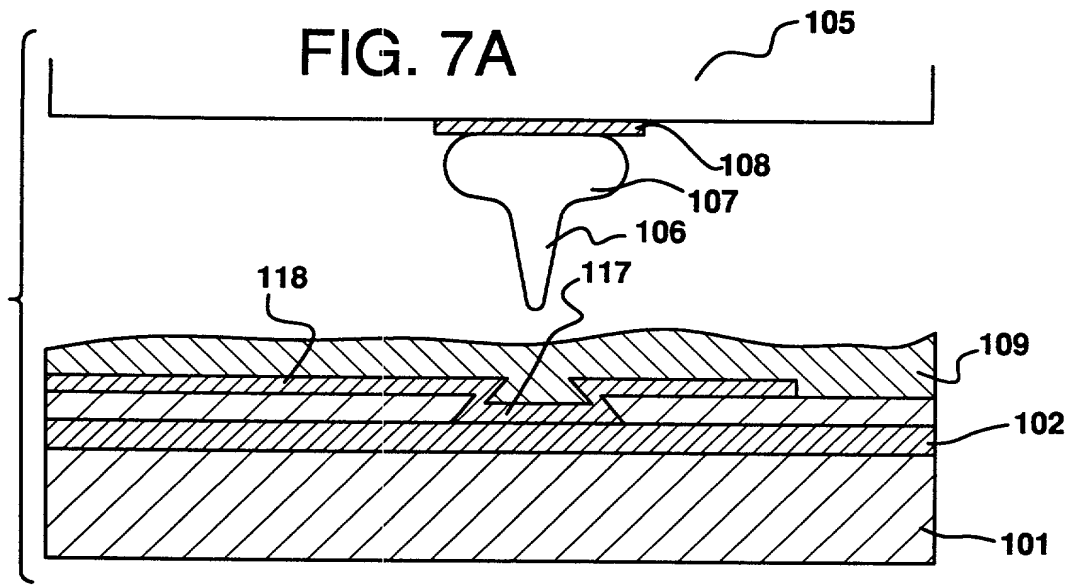


FIG. 8A

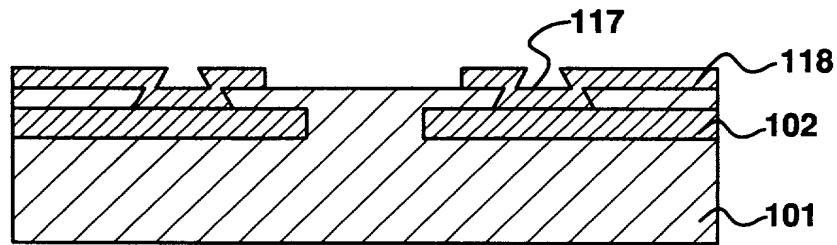


FIG. 8B

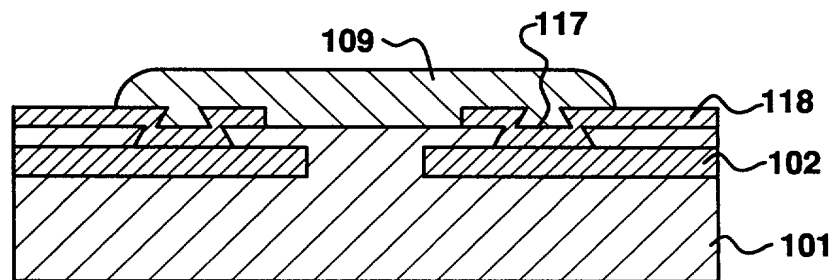


FIG. 8C

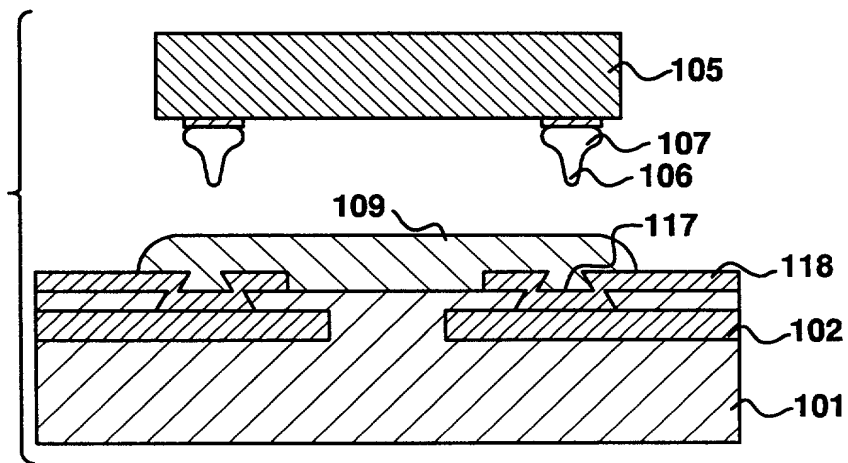


FIG. 8D

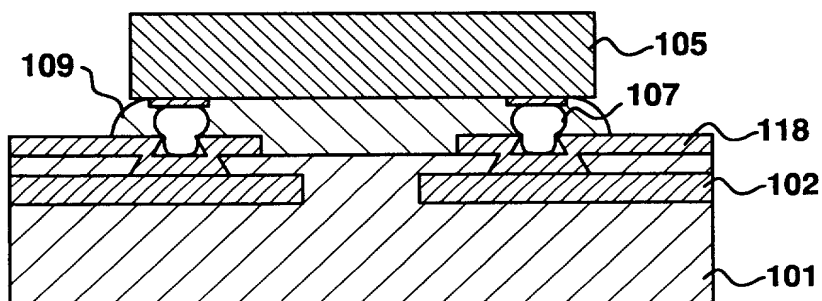


FIG. 9A

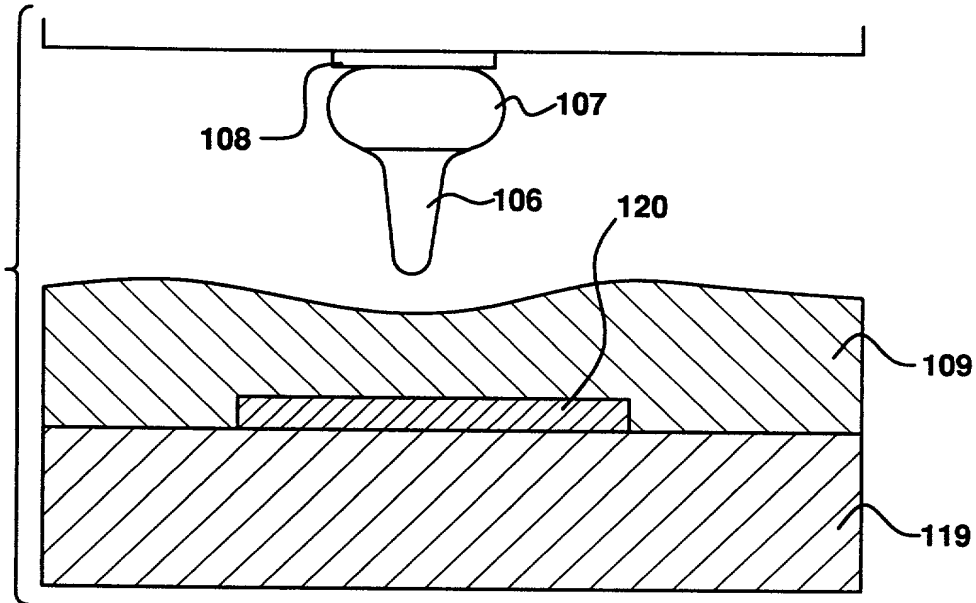


FIG. 9B

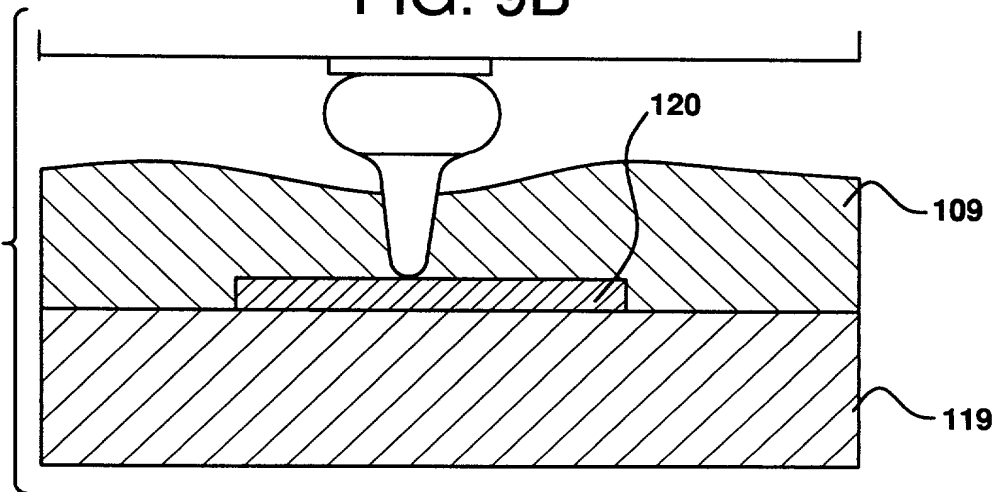
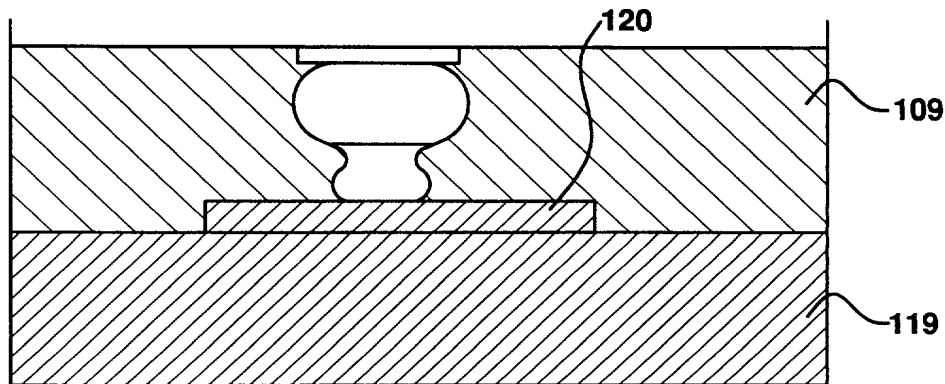


FIG. 9C



DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name: that I verily believe I am the original, first and sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of the subject matter claimed and for which a patent is sought in the application entitled:

METHOD OF MOUNTING A SEMICONDUCTOR DEVICE TO A SUBSTRATE AND A MOUNTED STRUCTURE

which application is:

☒ the attached application
(for original application)

☐ application Serial No. _____
filed _____, and amended on _____

(for declaration not accompanying application)

that I have reviewed and understand the contents of the specification of the above-identified application, including the claims, as amended by any amendment referred to above; that I acknowledge my duty to disclose information of which I am aware and which is material to the examination of this application under 37 C.F.R. 1.56; and that I hereby claim foreign priority benefits under Title 35, United States Code §119, §172 or §365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified on said list any foreign application for patent or inventor's certificate on this invention having a filing date before that of the application on which priority is claimed:


Application Number	Country	Filing Date	Priority Claimed (yes or no)
191737/1995	Japan	July 27, 1995	yes

I hereby claim the benefit of Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in a listed prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge my duty to disclose any material information under 37 C.F.R. 1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial No.	Filing Date	Status (patented, pending, abandoned)
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I hereby appoint John H. Mion, Reg. No. 18,879; Donald E. Zinn, Reg. No. 19,046; Thomas J. Macpeak, Reg. No. 19,292; Robert J. Seas, Jr., Reg. No. 21,092; Darryl Mexic, Reg. No. 23,063; Robert V. Sloan, Reg. No. 22,775; Peter D. Olexy, Reg. No. 24,513; J. Frank Osha, Reg. No. 24,625; Waddell A. Biggart, Reg. No. 24,861; Robert G. McMorow, Reg. No. 19,093; Louis Gubinsky, Reg. No. 24,835; Neil B. Siegel, Reg. No. 25,200; David J. Cushing, Reg. No. 28,703; John R. Inge, Reg. No. 26,916; Joseph J. Ruch, Jr., Reg. No. 26,577; Sheldon I. Landsman, Reg. No. 25,430; Richard C. Turner, Reg. No. 29,710; Howard L. Bernstein, Reg. No. 25,665; Alan J. Kasper, Reg. No. 25,426; Kenneth J. Burchfiel, Reg. No. 31,333; Gordon Kit, Reg. No. 30,764; Susan J. Mack, Reg. No. 30,951; Frank L. Bernstein, Reg. No. 31,484; Mark Boland, Reg. No. 32,197; William H. Mandir, Reg. No. 32,156; Scott M. Daniels, Reg. No. 32,562; and Brian W. Hannon, Reg. No. 32,778, my attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith, and request that all correspondence about the application be addressed to SUGHRUE, MION, ZINN, MACPEAK & SEAS, 2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

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 Residence _____ Signature _____
 Post Office Address _____
 Citizenship _____

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